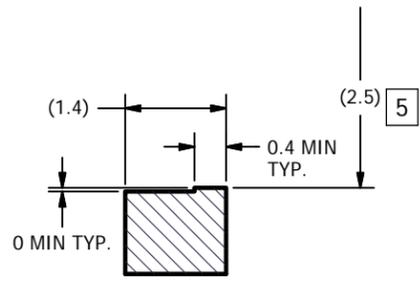
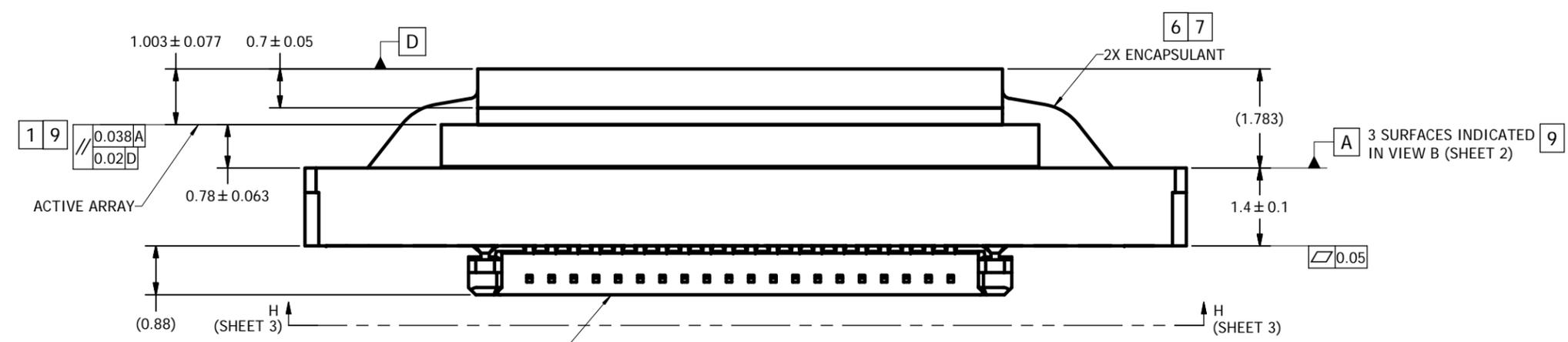
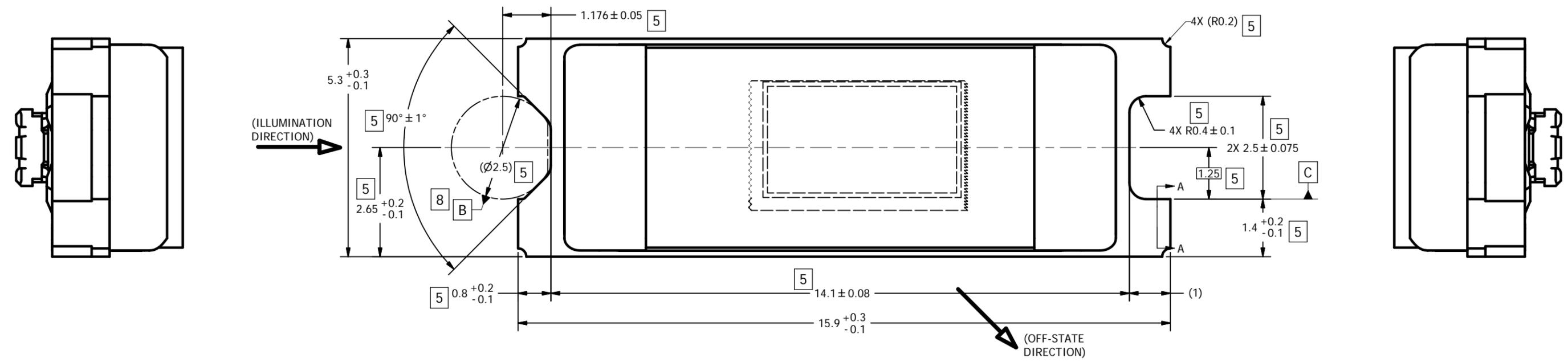


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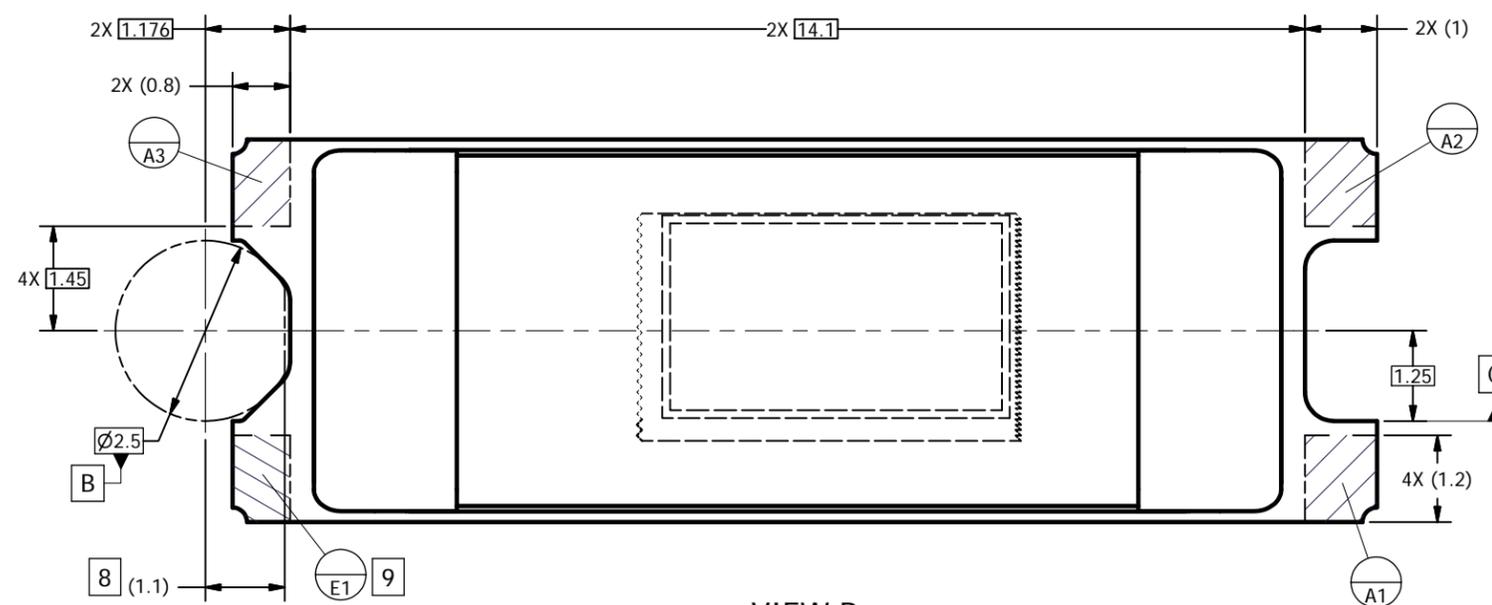
REVISIONS			
REV	DESCRIPTION	DATE	BY
A	ECO 2127544: INITIAL RELEASE	9/14/2012	BMH
B	ECO 2129552: ENLARGE APERTURE ON RIGHT SIDE; MOVE ACTIVE ARRAY Y-LOCATION DIM. SH. 3	12/10/2012	BMH
C	ECO 2131252: ENLARGE APERTURE ALONG BOTTOM EDGE	2/20/2013	BMH
D	ECO 2135244: CORRECT WINDOW THK TOL, ZONE B6	8/5/2013	BMH
E	ECO 2138016: INCREASE WINDOW THK NOMINAL	11/21/2013	BMH

- NOTES UNLESS OTHERWISE SPECIFIED:
- 1 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY.
  - 2 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND HAS A MAXIMUM ALLOWED VALUE OF 0.6 DEGREES.
  - 3 BOUNDARY MIRRORS SURROUNDING THE DMD ACTIVE ARRAY.
  - 4 DMD MARKING TO APPEAR IN CONNECTOR RECESS.
  - 5 NOTCH DIMENSIONS ARE DEFINED BY UPPERMOST LAYERS OF CERAMIC, AS SHOWN IN SECTION A-A.
  - 6 ENCAPSULANT TO BE CONTAINED WITHIN DIMENSIONS SHOWN IN VIEW C (SHEET 2). NO ENCAPSULANT IS ALLOWED ON TOP OF THE WINDOW.
  - 7 ENCAPSULANT NOT TO EXCEED THE HEIGHT OF THE WINDOW.
  - 8 DATUM B IS DEFINED BY A DIA. 2.5 PIN, WITH A FLAT ON THE SIDE FACING TOWARD THE CENTER OF THE ACTIVE ARRAY, AS SHOWN IN VIEW B (SHEET 2).
  - 9 WHILE ONLY THE THREE DATUM A TARGET AREAS A1, A2, AND A3 ARE USED FOR MEASUREMENT, ALL 4 CORNERS SHOULD BE CONTACTED, INCLUDING E1, TO SUPPORT MECHANICAL LOADS.

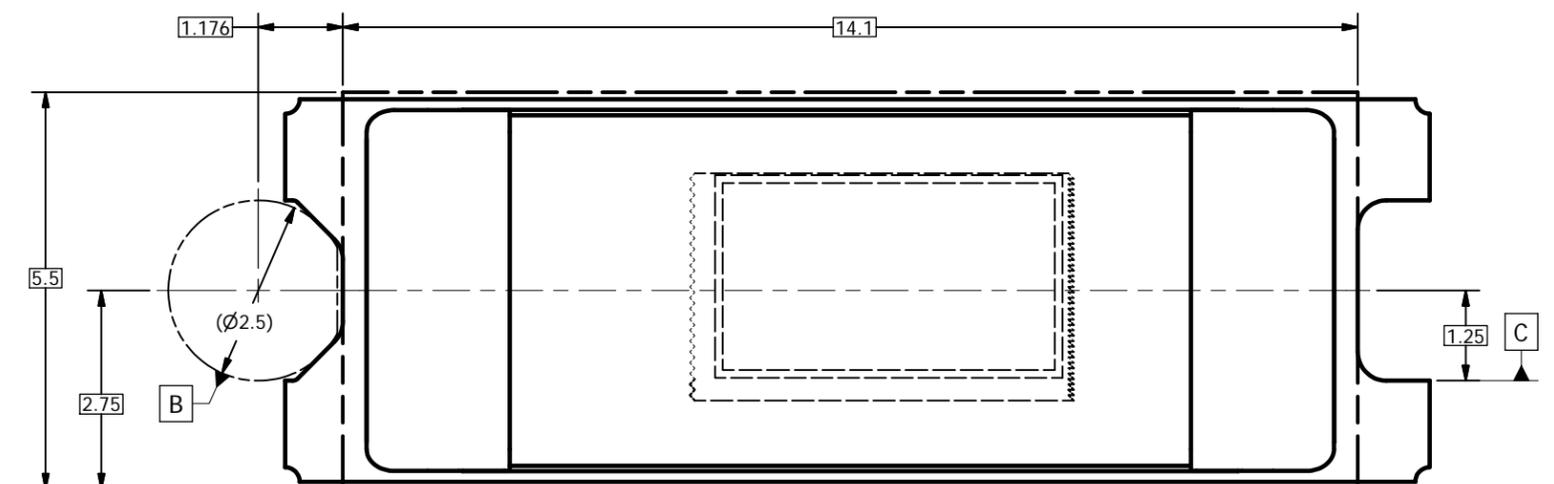


(PANASONIC AXT640124DD1, 40-CONTACT, 0.4 mm PITCH BOARD-TO-BOARD CONNECTOR HEADER) MATES WITH PANASONIC AXT540124DD1 OR EQUIVALENT CONNECTOR SOCKET

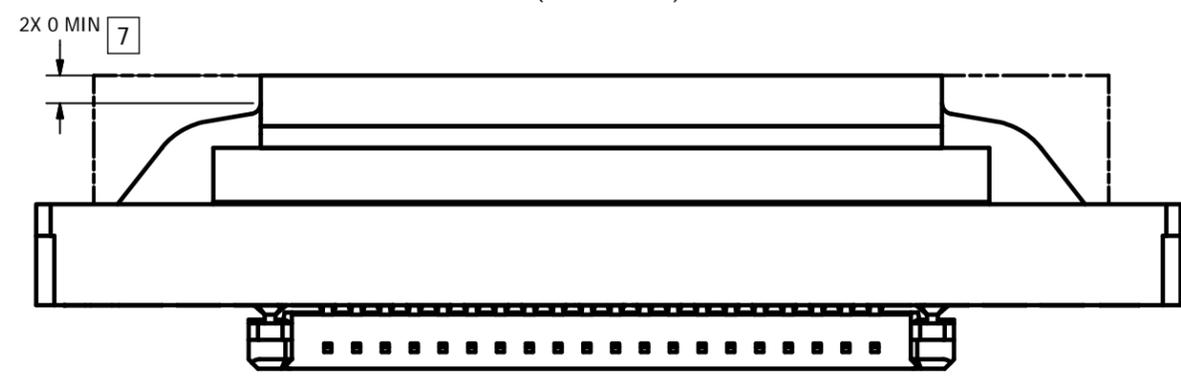
UNLESS OTHERWISE SPECIFIED ● DIMENSIONS ARE IN MILLIMETERS ● TOLERANCES: ANGLES ± 1° 2 PLACE DECIMALS ± 0.25 1 PLACE DECIMALS ± 0.50 ● DIMENSIONAL LIMITS APPLY BEFORE PROCEEDING ● INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994 ● REMOVE ALL BURRS AND SHARP EDGES ● PARENTHETICAL INFORMATION FOR REFERENCE ONLY	DRAWN B. HASKETT ENGINEER B. HASKETT QA/CE P. KONRAD CM F. ARMSTRONG	DATE 9/14/2012 9/14/2012 9/26/2012 9/26/2012	TEXAS INSTRUMENTS Dallas, Texas TITLE ICD, MECHANICAL, DMD, .2 WVGA SERIES 244
	APPROVED M. DORAK M. SOUCEK	DATE 9/18/2012 9/18/2012	



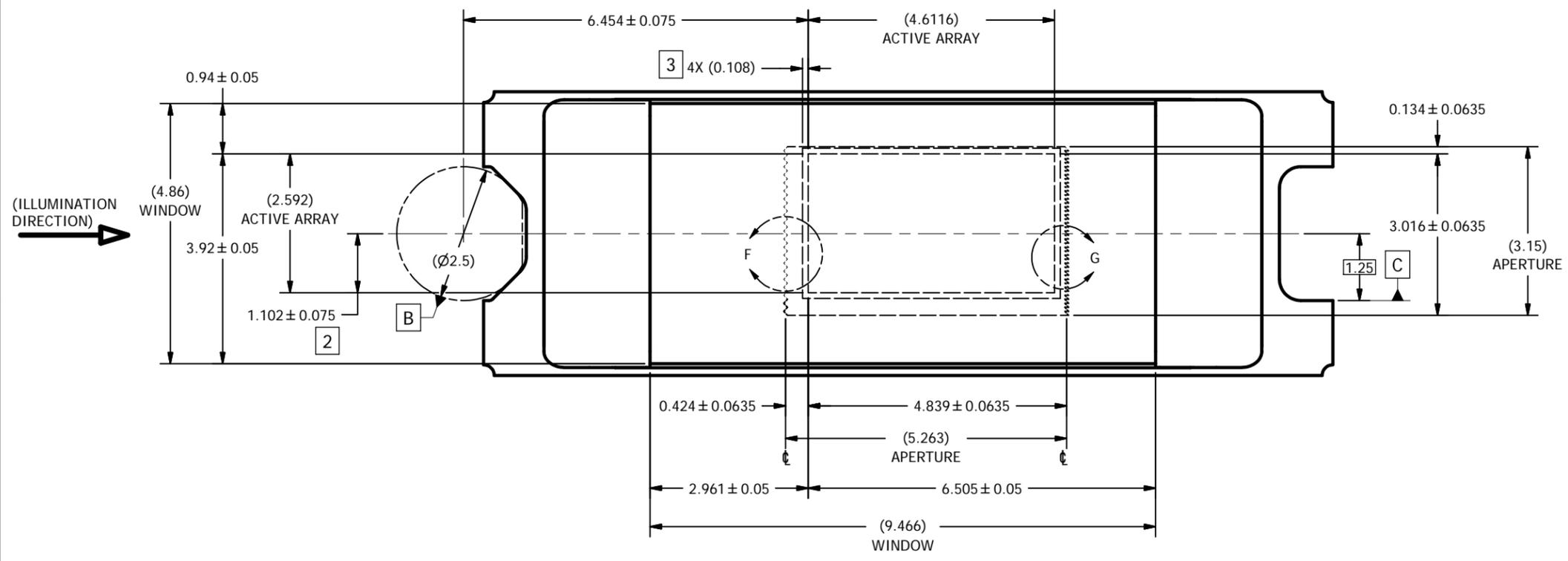
VIEW B  
DATUMS A, B, C, AND E  
(FROM SHEET 1)



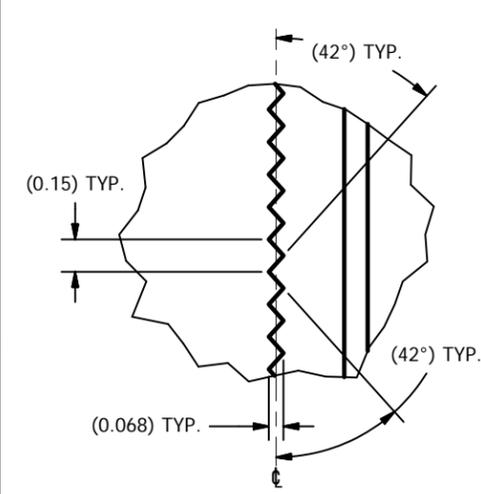
VIEW C <sup>6</sup>  
ENCAPSULANT MAXIMUM X/Y DIMENSIONS  
(FROM SHEET 1)



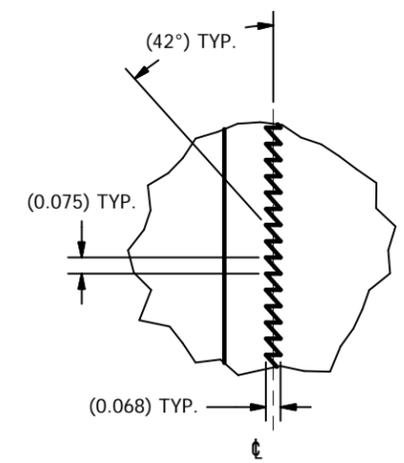
VIEW D  
ENCAPSULANT MAXIMUM HEIGHT



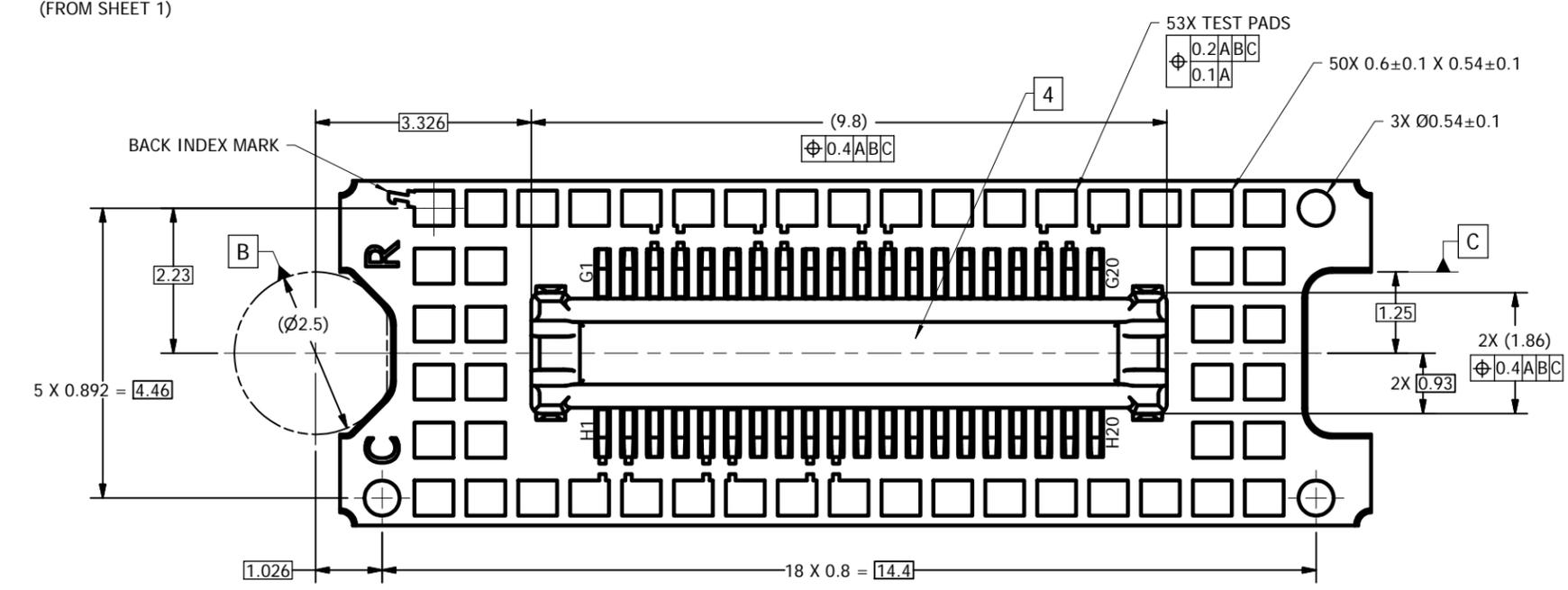
VIEW E  
WINDOW AND ACTIVE ARRAY  
(FROM SHEET 1)



DETAIL F  
APERTURE LEFT EDGE  
SCALE 60 : 1



DETAIL G  
APERTURE RIGHT EDGE  
(POND OF MIRRORS OMITTED FOR CLARITY)  
SCALE 60 : 1



VIEW H-H  
TEST PADS AND CONNECTOR  
(FROM SHEET 1)

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